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Semiconductors and Heterogeneous Integration

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Message from the Editor-in-Chief

Semiconductors and Heterogeneous Integration is committed to publishing rigorous, peer-reviewed research in semiconductor science and integration technology that deepens scientific understanding and accelerates technological translation for advanced integration circuit manufacturing. In addition to regular articles, reviews, and short communications, we offer an express track for the rapid dissemination of breakthrough discoveries. We also welcome visionary perspectives that challenge conventional paradigms and illuminate emerging directions.

Our editorial board comprises leading experts from around the world, reflecting the global and interdisciplinary nature of this field. We are dedicated to upholding the highest standards of scholarship, inclusivity, and transparency.

To our readers, contributors, and reviewers: thank you for joining us on this exciting journey. Together, we will shape the discourse, define the challenges, and celebrate the innovations that will drive the next wave of semiconductor technology advancement.

Editor-in-Chief
Prof. Dr. Hei Wong

Aims

Semiconductors and Heterogeneous Integration (ISSN 3042-9013) is an international, peer-reviewed, open access journal dedicated to advancing innovations in semiconductor science and technology in the post-Moore era. The journal publishes original research articles, comprehensive reviews, and communications at the intersection of advanced semiconductors and heterogeneous integration. Submissions are expected to include detailed experimental data and theoretical analysis to ensure scientific rigor and reproducibility.

Scope

Novel semiconductor materials
- Compound semiconductors
- Engineered substrate materials
- Other novel semiconductors and functional materials

Advanced heterogeneous integration technologies
- Materials integration
- Multidimensional integration
- Integration processes and packaging technologies

Advanced characterization and testing techniques
- Heterogeneous materials and structures analysis
- Advanced microstructural analysis
- Reliability analysis

Heterogeneously integrated systems and applications
- High-performance computing
- Optoelectronic integrated systems
- Intelligent sensor networks
- Power delivery networks

Modeling and Design Automation
- Multiphysics modeling and simulation
- Co-design and co-optimization
- Chiplet design automation

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